

PATENT ABSTRACTS OF JAPAN

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(21)Application number : 62-077796 (71)Applicant : FUJITSU LTD

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(54) CALIBRATION OF WAFER SURFACE INSPECTING DEVICE

(57)Abstract:

PURPOSE: To contrive so as not to be confused an adhered foreign substance with intentional foreign substances provided on a calibration wafer and to make it possible to prevent the lowering of the calibration accuracy even though the foreign substance is adhered on the wafer by a method wherein an antireflection film is provided on the surface of the substrate of the wafer.



CONSTITUTION: An antireflection film 23, which consists of Si dioxide or Si nitride (SiN) and acts as reflection prevention to the wavelength of the incident light of a wafer inspecting device, is formed on a substrate 21, which consists of a clean Si wafer, of a calibration wafer and moreover, an Si nitride film or an Si dioxide film (The material is made to differ from that of the film 23.) formed thereon is patterned and a plurality of intentional foreign substances 22 distributed sparsely, such as in the form of a 1-mm interval matrix, are formed. The thickness of the film 23 is about 1000 Å in the film consisting of Si dioxide in case the wavelength of the incident light is 6330 Å (The light source is a helium-neon laser.) and is about 800 Å in the film consisting of Si nitride. When this calibration wafer is used, an adhered foreign substance adhered on the film 23 is detected very small than its actual size in a state to say that even a big foreign substance of 2 μ m, for example, is detected as a foreign substance of 0.4 μ m.

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